



1. **Maker : TEL/Tokyo Electron Limited**
2. **Model : Clean Track ACT 8**
3. **Serial Number :**
4. **Vintage : 2001**
5. **Description : Photo Resist Coat and Develop System**
6. **Configuration**

1) **Block Diagram (Left to Right Wafer Flow)**

SUC (1-3)	CRA 1-0 	2-24 HHP	2-29 LHP	2-14 HHP	3-4 WEE			
		2-23 PHP	2-28 LHP	2-13 LHP				
		2-22 PHP	2-27 LHP	2-12 CPL				
		2-21 PHP	2-26 LHP	2-11 CPL				
		2-20 RSV	2-25 LHP	2-10 CWH	3-0 IRA 	3-5 EIS		
		2-19 PHP		2-09 CPL				
		SUC (1-2)		2-08 RSV	2-0 PRA	2-18 RSV		
				2-07 ADH		2-17 CPL		
				2-06 TRS		2-16 TRS		
				2-05 TCP		2-15 CPL	3-3 SBU	
SUC (1-1)		2-3 DEV	2-4 DEV	3-2 SBU				
		2-1 COT	2-2 COT	3-1 THS				

Chemical Supply System
 HMDS, Develop and Solvent Supply

Thermo Control Unit
 INR-244

AC Power Rack

2) **Chemical Cabinet Details**

1 2-7 ADH HMDS Buffer Tank Tray	2 Solvent Filter Tray	3 DEV Filter Tray	
4 Solvent 3L Buffer Tank 2ea	5 Solvent Degas Tray	6 DEV Degas Tray	7 DEV 3L Buffer Tank 2ea

3) Detailed Hardware Specification

- A. Wafer Size : 200mm, DUV Application, Single Block System
- B. Wafer Flow : Left to Right (CSB Unit is in Left side and Interface Station Unit is in Right side)
- C. Process Block : 1ea (Single Block System)
- D. Block #1
 - a. TEL Clean Track ACT 8 EC/Equipment Controller Type#2
 - b. Stage/Indexer : 3 SMIF Integrated CSB/Cassette Stage Block
 - c. CRA/Cassette Block Robotics Arm : 1ea
 - d. FFU: Installed
- E. Block #2
 - a. 2-1 Standard Coat Unit
 - ① 4 Standard Photo Resist Dispense Nozzles
 - ② 4 TEL OEM RRC F-T100-2 Photo Resist Pumps
 - ③ 1 Solvent Pre-wet RRC/Reduced Resist Coat Nozzle
 - ④ 1 Side Rinse Nozzle (Programmable Side Rinse EBR)
 - ⑤ Dual Back Rinse Nozzles
 - ⑥ Coat Cup Temperature Synchronized Control System
 - ⑦ Photo Resist Temperature Control
 - ⑧ Motor Flange Temperature Control
 - ⑨ Photo Resist Drain Type : Direct Gravity Drain Type
 - ⑩ Auto Dummy Dispense System
 - ⑪ Photo Resist Bottle Quantity :

	Resist #1	Resist #2	Resist #3	Resist #4
COT 2-1	1 Bottle	1 Bottle	1 Bottle	1 Bottle
COT 2-2	1 Bottle	1 Bottle	1 Bottle	1 Bottle

- b. 2-1 Standard Coat Unit : Same as 2-1 Standard Coat Unit
- c. 2-3 Develop Unit
 - ① 1 H Nozzle
 - ② Develop Temperature Control
 - ③ Motor Flange Temperature Control
 - ④ Drain Type : Direct Gravity Drain Type
 - ⑤ Top Rinse Nozzle
 - ⑥ Dual Back Rinse Nozzle

- ⑦ Auto Damper
- ⑧ Auto Dummy Dispense System
- d. 2-4 Develop Unit : Same as 2-3 Develop Unit
- e. PRA/Process Block Robotics Arm: 1ea
- f. Plate Units
 - ① ADH/Adhesion Process Station: 1ea
 - ② HHP/High Temperature Hot Plate Station : 2ea
 - ③ LHP/Low Temperature Hot Plate Station : 6ea
 - ④ CPL/Chilling Plate Process Station : 5ea
 - ⑤ TRS/Transition Stage Unit : 2ea
 - ⑥ TCP/Transition Chilling Plate : 1ea
 - ⑦ PHP/High Precision Hot Plate Process Station : 4ea
 - ⑧ CWH/Cup Washer Holder Unit : 1ea
- F. Block #3 : Standard Interface Block
 - a. IRA/Interface Robotics Arm : 1ea
 - b. Interfaced for NIKON 2205EX14C
 - c. WEE/Wafer Edge Exposure Process Station : 1ea
 - d. THS/Temporary Holding Stage : 1ea
 - e. SBU/Stationary Buffer Unit : 2ea
 - f. TRS/Transition Stage Unit : N/A
 - g. CPL/Chill Plate Process Station : N/A
 - h. EIS/Interface Stage Module : 1ea
 - i. FFU: Installed
- G. T&H/Temperature and Humidity Controller : N/A
- H. External Chemical Supply System/Cabinet (HMDS, Solvent, DEV Solutions)
 - a. HMDS Supply System
 - ① HMDS Chemical Type: 1ea
 - ② Bulk-Fill CSS/Central Chemical Supply Type with 3 Liter Teflon Buffer Tanks (1)
 - ③ 1 Buffer Tank (3 Liter/Tank, Teflon, N2 Bubbling) for 1 ADH Unit
 - b. Solvent Supply System for 2 Standard Coat Units (2-1, 2-2)
 - ① Solvent Chemical Type: 1ea
 - ② Bulk-fill CSS/Central Chemical Supply Type with 3Liter Teflon Buffer Tanks (2)

- ③ 2 Buffer Tanks (3 Liter/Tank, Teflon) to support 2 Standard Coat Units (2-1, 2-2)
- c. Developer Supply System for 2 Develop Units (2-3, 2-4)
 - ① Developer Chemical Type: 1ea
 - ② Bulk-Fill CSS/Central Chemical Supply Type with 3 Liter Teflon Buffer Tanks (2)
 - ③ 2 Buffer Tanks (3 Liter/Tank, Teflon) to support 2 Develop Units (2-3, 2-4)
- I. TEL OEM TCU/Temperature Control Unit : 1ea
(SMC Circulator Pumps and Thermo Controller with 9 Channels)
 - a. 2 Chilling Channels for 2 Coat Spin Units
 - b. 2 Chilling Channel for 2 Develop Units
 - c. 5 Chilling Channel for 5 CPL/Chill Plate Process Station Units
- J. Power Transformer AC Cabinet : 208VAC, 3 Phases, 50/60Hz
- K. Software Options : Hard Disk Removed
- L. Utility connection Position : Bottom/Back Side

7. Important Notice

- 1) This Document could contain typographical errors or technical inaccuracies.